

## Description

The LYT52AA05UL is a uni-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. It complies with IEC 61000-4-2 (ESD),  $\pm 25\text{kV}$  air and  $\pm 20\text{kV}$  contact discharge. It is assembled into a lead-free SOT-523 package. It is designed to protect HDMI, MDDI, antenna circuits, USB 2.0 etc.

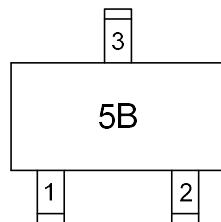
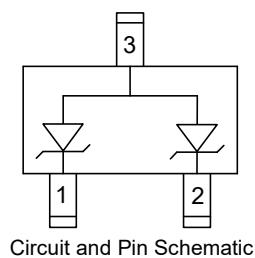
## Features

- Low clamping voltage
- Ultra low leakage current
- Operating voltage: 5V
- RoHS compliant
- IEC-61000-4-2 ESD  $\pm 25\text{kV}$  Air,  $\pm 20\text{kV}$  Contact
- Packaging: 7 inch reel, 3000pcs/reel

## Applications

- Wireless bandwidth Transceiver Protection
- HBT Power Amplifier Protection
- Photodetector Protection
- Firewire Ports
- USB 2.0
- MDDI

## Pin Configuration and Marking



## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )

Parameter	Symbol	Value
Peak Pulse Power (8/20μs)	$P_{PP}$	80W
Peak Pulse Current (8/20μs)	$I_{PP}$	5A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	±25kV ±20kV
Ambient Temperature Range	$T_A$	-55°C to +125°C
Storage Temperature Range	$T_{STG}$	-55°C to +150°C

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ )

Parameter	Symbol	Test Condition	Min.	Typ.	Max.
Reverse Working Voltage	$V_{RWM}$		-	-	5V
Breakdown Voltage	$V_{BR}$	$I_T = 1\text{mA}$	6V	-	-
Reverse Leakage Current	$I_R$	$V_{RWM} = 5\text{V}$	-	-	0.5μA
Clamping Voltage	$V_C$	$I_{PP} = 1\text{A}$ (8/20μs)	-	-	9V
		$I_{PP} = 5\text{A}$ (8/20μs)	-	-	16V
Junction Capacitance	$C_J$	$V_R = 0\text{V}$ , $f = 1\text{MHz}$	-	0.6pF	0.8pF

## Typical Characteristic Curves ( $T_A=25^\circ\text{C}$ )

Figure 1. Peak Pulse Power Rating Curve

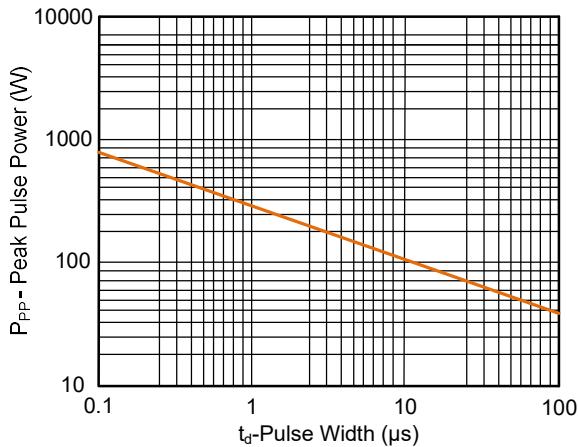


Figure 2. Pulse Derating Curve

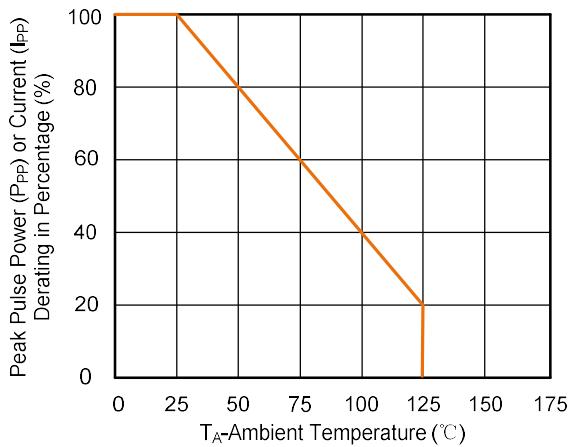


Figure 3. Clamping Voltage vs. Peak Pulse Current

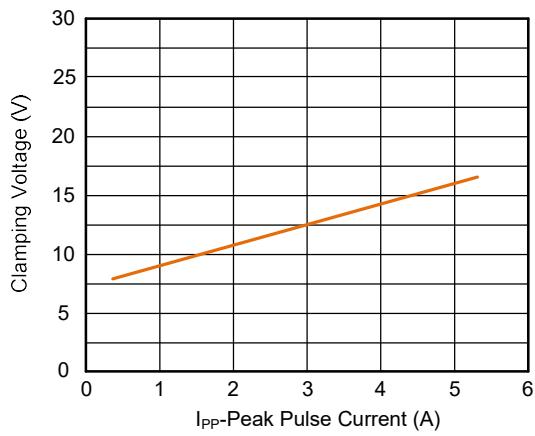


Figure 4. Junction Capacitance vs. Reverse Voltage

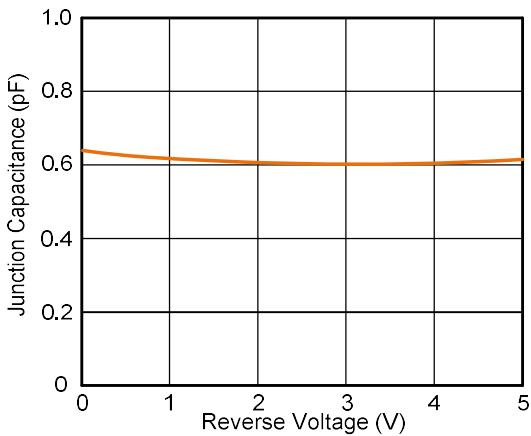


Figure 5. Pulse Waveform (8/20μs)

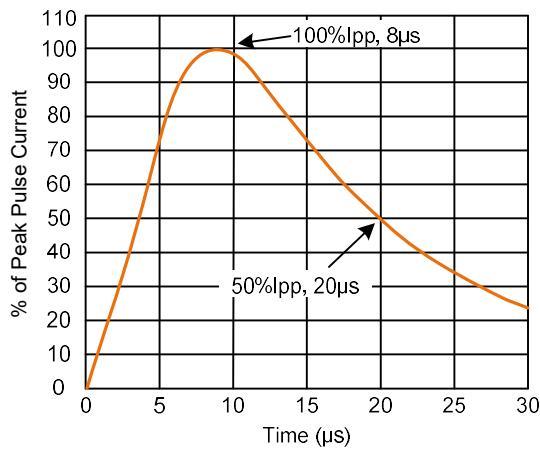
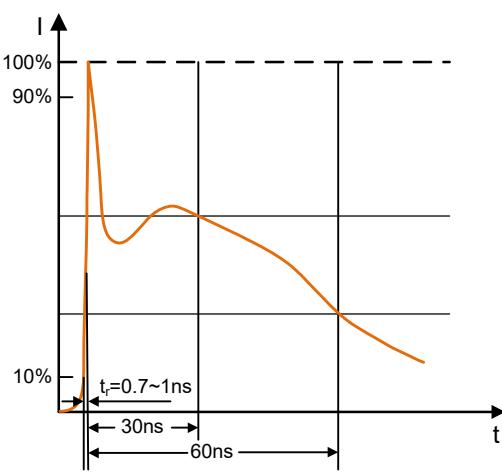
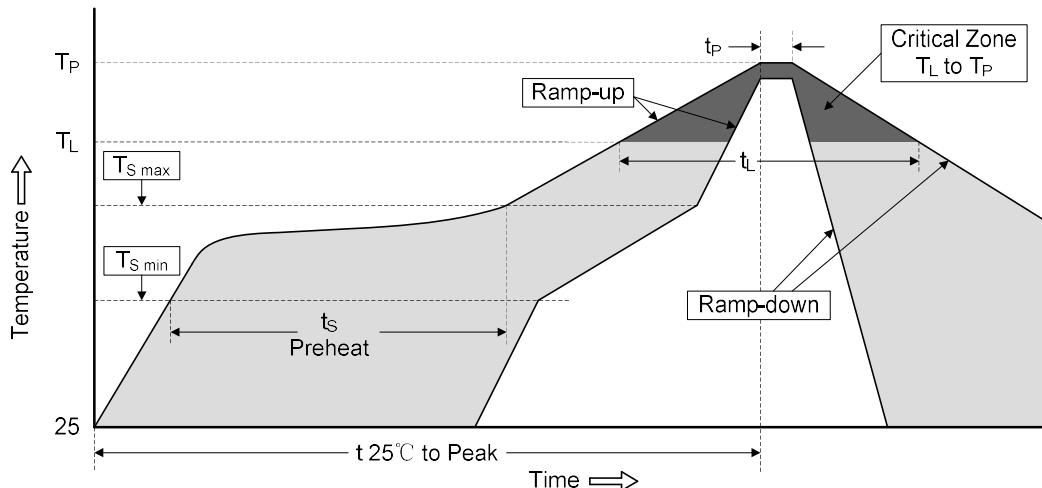


Figure 6. Pulse Waveform (IEC61000-4-2)



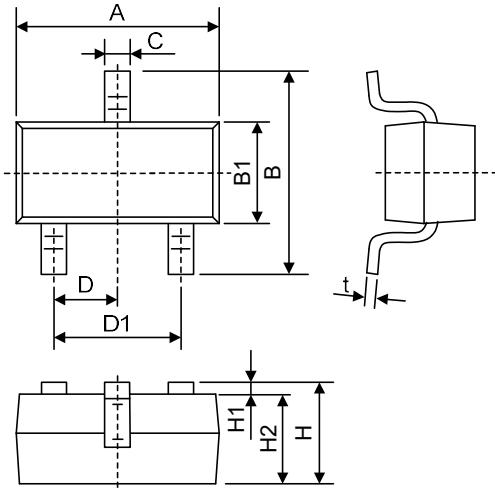
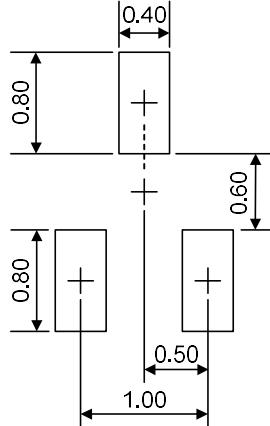
## Soldering Parameters

### Reflow Soldering



Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat	
-Temperature Min ( $T_{S\ min}$ )	150°C
-Temperature Max ( $T_{S\ max}$ )	200°C
-Time (min to max) ( $t_s$ )	60-180 seconds
$T_{S\ max}$ to $T_L$	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature ( $T_L$ )	217°C
-Time ( $t_L$ )	60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_P$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

## Dimensions (SOT-523)

Recommended Solder Pad Layout (mm)

Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.50	1.70	0.059	0.067
B	1.45	1.75	0.057	0.069
B1	0.75	0.85	0.029	0.033
C	0.15	0.30	0.005	0.012
D	0.50BSC		0.020BSC	
D1	1.00BSC		0.039BSC	
H	0.60	0.90	0.023	0.035
H1	0.00	0.10	0.000	0.004
H2	0.60	0.80	0.023	0.031
t	0.10	0.20	0.003	0.008